

09/732,821

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,821,821 B2
DATED : November 23, 2004
INVENTOR(S) : Joseph Fjelstad

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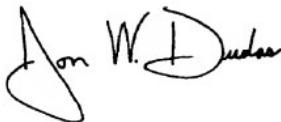
It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 3.

Lines 35-37, "chip package having a second semiconductor chip back-bonded to the first chip such separate" should read -- chip package having a separate --.

Signed and Sealed this

Tenth Day of May, 2005



JON W. DUDAS
Director of the United States Patent and Trademark Office